

PHD**BPC150A 1K6V....SERIES****SINGLE-PHASE RECTIFIER SERIES****Features**

- Low V_F
- Direct Mounting to heatsink
- Low profile package
- Glass Passivation Chip
- Easy Connection
- Insulated Type

Typical Applications

- Inverters
- Welding
- UPS
- SMPS
- Battery Chargers
- DC Motors
- General Purpose DC Power Supplies

Major Ratings and Characteristics

Parameters	BPC150A 1K6V	Units
I_o	150	A
@ T_c	105	°C
I_{FSM}	600	A
@ 50Hz	620	A
I^2t	1370	A^2s
@ 60Hz	1230	A^2s
V_{DRM}/V_{RRM}	400 to 1600	V
T_j range	- 40 to 150	°C

ELECTRICAL SPECIFICATIONS**Voltage Ratings**

Type number	Voltage Code	V_{RRM}/V_{DRM} , maximum repetitive peak reverse voltage V	V_{RSM} , maximum non- repetitive peak rev. voltage V	I_{RRM}/I_{DRM} max. @ $T_J = T_{J\max}$ mA
BPC150A..	04	400	500	5
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

Forward Conduction

Parameter	BPC150A.	Units	Conditions					
I_o Maximum DC output current @ Case temperature	150	A	120° Rect conduction angle					
	105	°C						
I_{FSM} , Maximum peak, one-cycle forward, non-repetitive on state surge current	600	A	t = 10ms	No voltage reapplied	Initia $T_J = T_{J\max}$			
	620		t = 8.3ms					
	430		t = 10ms	100% V_{RRM} reapplied				
	460		t = 8.3ms					
$I^2 t$ Maximum $I^2 t$ for fusing	1370	$A^2 s$	t = 10ms	No voltage reapplied				
	1230		t = 8.3ms					
	620		t = 10ms	100% V_{RRM} reapplied				
	690		t = 8.3ms					
$I^2 \sqrt{t}$ Maximum $I^2 \sqrt{t}$ for fusing	15100	$A^2 \sqrt{s}$	t = 0.1 to 10ms, no voltage reapplied					
V_{FM} Maximum forward voltage drop	1.25	V	$V_{FM} = 1.25$ V, $T_J = 25^\circ C$, $t_p = 400 \mu s$ single junction					

Thermal and Mechanical Specifications

Parameter	BPC150A	Units	Conditions
T _J	Maximum junction operating temperature range	- 40 to 150	°C
T _{stg}	Maximum storage temperature range	- 40 to 150	°C
R _{thJC}	Maximum thermal resistance, junction to case	0.1	DC operation per module
		1.0	DC operation per junction
		0.12	120° Rect conduction angle per module
		1. 0	120° Rect conduction angle per junction
R _{thJC}	Maximum I ² √ t for fusing	0.10	K/W Per module. Mounting surface smooth, flat and greased. Heatsink compound thermal conductivity = 0.42W/mK
T	Mounting torque ± 10% to heatsink	3	Nm A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound.Lubricated threads.
wt	Approximate weight	350	g

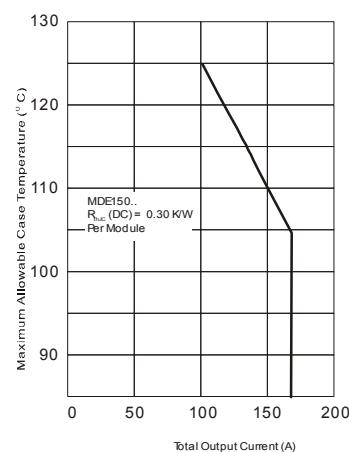
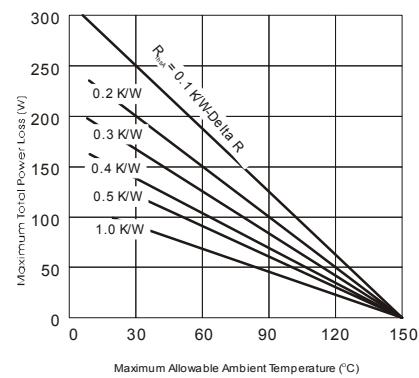
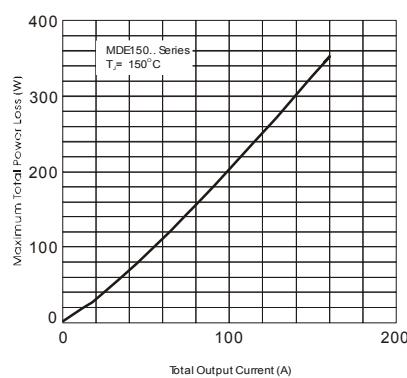


Fig. 1 - Current Rating Characteristics



Outline Table

